502413521 07/10/2013

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ying-Chih Chen	06/15/2005
Chiu-Ming Chou	06/15/2005
Mou-Shiung Lin	06/15/2005

RECEIVING PARTY DATA

Name:	Megic Corporation		
Street Address:	No. 21, R&D 1st Road, Science-Based Industrial Park		
City:	Hsinchu		
State/Country:	TAIWAN		
Postal Code:	ROC		

PROPERTY NUMBERS Total: 1

Property Type	Number		
Patent Number:	7919412		

CORRESPONDENCE DATA

Fax Number: 8586582502

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: (858) 651-5205

Email: usdocketing@qualcomm.com
Correspondent Name: QUALCOMM Incorporated
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ATTORNEY DOCKET NUMBER:	093035C1		
NAME OF SUBMITTER:	Karen M Cruz		
Signature:	/Karen M Cruz/		
Date:	07/10/2013		

Total Attachments: 2 source=093035#page1.tif source=093035#page2.tif

> PATENT REEL: 030766 FRAME: 0167

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ASSIGNMENT

WHEREAS, 1, Ying-Chih Chen

2. Chiu-Ming Chou

3. Mou-Shiung Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: OVER-PASSIVATION PROCESS AND PROCESS OF FORMING A POLYMER ON THE CHIP

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Megic Corporation of No. 21, R&D 1st Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature:	Y7n#	-Chih	Che-	Date:	2015/6/15
	1				

Sole or First Joint Inventor: Ying-Chin Chen

Signature: Chiu - Mis Chen Date: >705/6/15

Second Joint Inventor: Chiu-Ming Chou

ignature: Muss fig. Date: June 15, 2005

Third Joint Inventor: Mou-Shlung Lin